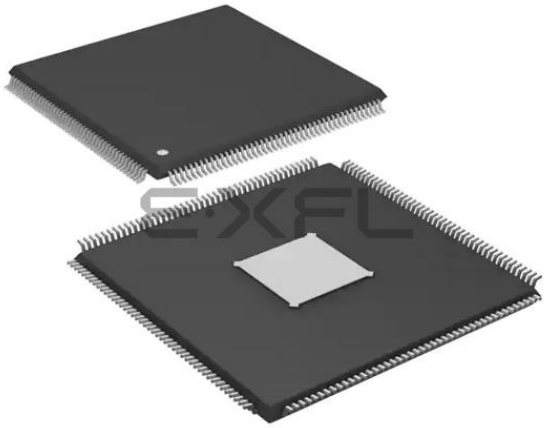

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Fixed/Floating Point
Interface	CAN, EBI/EMI, Ethernet, DAI, I²C, MMC/SD/SDIO, SPI, SPORT, UART/USART, USB OTG
Clock Rate	300MHz, 300MHz
Non-Volatile Memory	External
On-Chip RAM	1.768MB
Voltage - I/O	3.30V
Voltage - Core	1.10V
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP Exposed Pad
Supplier Device Package	176-LQFP-EP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/adsp-sc571kswz-3

SYSTEM MEMORY MAP

Table 4. L1 Block 0, Block 1, Block 2, and Block 3 SHARC+® Addressing Memory Map (Private Address Space)

Memory	Long Word (64 Bits)	Extended Precision/ ISA Code (48 Bits)	Normal Word (32 Bits)	Short Word/ VISA Code (16 Bits)	Byte Access (8 Bits)
L1 Block 0 SRAM (1 Mb)	0x00048000–0x0004BFFF	0x00090000–0x00095554	0x00090000–0x00097FFF	0x00120000–0x0012FFFF	0x00240000–0x0025FFFF
L1 Block 1 SRAM (1 Mb)	0x00058000–0x0005BFFF	0x000B0000–0x000B5554	0x000B0000–0x000B7FFF	0x00160000–0x0016FFFF	0x002C0000–0x002DFFFF
L1 Block 2 SRAM (0.5 Mb)	0x00060000–0x00061FFF	0x000C0000–0x000C2AA9	0x000C0000–0x000C3FFF	0x00180000–0x00187FFF	0x00300000–0x0030FFFF
L1 Block 3 SRAM (0.5 Mb)	0x00070000–0x00071FFF	0x000E0000–0x000E2AA9	0x000E0000–0x000E3FFF	0x001C0000–0x001C7FFF	0x00380000–0x0038FFFF

Table 5. L2 Memory Addressing Map

Memory[1]	Byte Address Space ARM Cortex-A5—Data Access and Instruction Fetch SHARC+—Data Access	Normal Word Address Space SHARC+ Data Access	VISA Address Space SHARC+ Instruction Fetch	ISA Address Space SHARC+ Instruction Fetch
L2 Boot ROM0[2]	ARM: 0x00000000–0x00007FFF SHARC/DMA: 0x20100000–0x20107FFF	0x08040000–0x08041FFF	0x00B20000–0x00B23FFF	0x00580000–0x00581555
L2 RAM (8 Mb)	0x20000000–0x200FFFFF	0x08000000–0x0803FFFF	0x00B80000–0x00BFFFFF	0x005C0000–0x005EAAAA
L2 Boot ROM1	0x20108000–0x2010FFFF	0x08042000–0x08043FFF	0x00B00000–0x00B03FFF	0x00500000–0x00501555
L2 Boot ROM2[3]	0x20110000–0x20117FFF	0x08044000–0x08045FFF	0x00B40000–0x00B43FFF	0x00540000–0x00541555

[1] All L2 RAM blocks are subdivided into eight banks.
[2] For ADSP-SC57x products, the L2 Boot ROM0 byte address space is 0x00000000–0x00007FFF.
[3] L2 Boot ROM address for ADSP-2157x products.

Table 6. SHARC+® L1 Memory in Multiprocessor Space

		Memory Block	Byte Address Space ARM Cortex-A5 and SHARC+	Normal Word Address Space SHARC+
L1 memory of SHARC1 in multiprocessor space	Address via Slave1 Port	Block 0	0x28240000–0x2825FFFF	0x0A090000–0x0A097FFF
		Block 1	0x282C0000–0x282DFFFF	0x0A0B0000–0x0A0B7FFF
		Block 2	0x28300000–0x2830FFFF	0x0A0C0000–0x0A0C3FFF
		Block 3	0x28380000–0x2838FFFF	0x0A0E0000–0x0A0E3FFF
L1 memory of SHARC2 in multiprocessor space	Address via Slave1 Port	Block 0	0x28A40000–0x28A5FFFF	0x0A290000–0x0A297FFF
		Block 1	0x28AC0000–0x28ADFFFF	0x0A2B0000–0x0A2B7FFF
		Block 2	0x28B00000–0x28B0FFFF	0x0A2C0000–0x0A2C3FFF
		Block 3	0x28B80000–0x28B8FFFF	0x0A2E0000–0x0A2E3FFF

Table 7. Memory Map of Mapped I/Os[1]

	Byte Address Space ARM Cortex-A5—Data Access and Instruction Fetch SHARC+—Data Access	Normal Word Address Space SHARC+ Data Access	VISA Address Space SHARC+ Instruction Fetch	ISA Address Space SHARC+ Instruction Fetch
SPI2 Memory (512 MB)	0x60000000–0x600FFFFF	0x04000000–0x07FFFFFF	0x00F80000–0x00FFFFFF	0x00780000–0x007FFFFF
	0x60100000–0x602FFFFF		Not applicable	
	0x60300000–0x6FFFFFFF		Not applicable	Not applicable
	0x70000000–0x7FFFFFFF	Not applicable	Not applicable	Not applicable

[1] The ARM Cortex-A5 can access the entire byte address space. The SHARC+ VISA/ISA address space for instruction fetch and the normal word address space for data access do not cover the entire byte address space.

The two capacitors and the series resistor, shown in Figure 6, fine tune phase and amplitude of the sine frequency. The capacitor and resistor values shown in Figure 6 are typical values only. The capacitor values are dependent upon the load capacitance recommendations of the crystal manufacturer and the physical layout of the printed circuit board (PCB). The resistor value depends on the drive level specified by the crystal manufacturer. The user must verify the customized values based on careful investigations on multiple devices over the required temperature range.

A third overtone crystal can be used for frequencies above 25 MHz. The circuit is then modified to ensure crystal operation only at the third overtone by adding a tuned inductor circuit, shown in Figure 6. A design procedure for third overtone operation is discussed in detail in "Using Third Overtone Crystals with the ADSP-218x DSP" (EE-168). The same recommendations can be used for the USB crystal oscillator.

Clock Distribution Unit (CDU)

The two CGUs each provide outputs which feed a clock distribution unit (CDU). The clock outputs CLKO0–CLKO9 are connected to various targets. For more information, refer to the ADSP-SC57x/ADSP-2157x SHARC+ Processor Hardware Reference.

Power-Up

SYS_XTALx oscillations (SYS_CLKINx) start when power is applied to the VDD_EXT pins. The rising edge of $\overline{\text{SYS\_HWRST}}$ starts on-chip PLL locking (PLL lock counter). The deassertion must apply only if all voltage supplies and SYS_CLKINx oscillations are valid (refer to the Power-Up Reset Timing section).

Clock Out/External Clock

The SYS_CLKOUT output pin has programmable options to output divided-down versions of the on-chip clocks. By default, the SYS_CLKOUT pin drives a buffered version of the SYS_ CLKIN0 input. Refer to the ADSP-SC57x/ADSP-2157x SHARC+ Processor Hardware Reference to change the default mapping of clocks.

Booting

The processors have several mechanisms for automatically loading internal and external memory after a reset. The boot mode is defined by the SYS_BMODE[n] input pins. There are two categories of boot modes. In master boot mode, the processors actively load data from serial memories. In slave boot modes, the processors receive data from external host devices.

The boot modes are shown in Table 9. These modes are implemented by the SYS_BMODE[n] bits of the reset configuration register and are sampled during power-on resets and software initiated resets.

In the ADSP-SC57x processors, the ARM Cortex-A5 (Core 0) controls the boot process, including loading all internal and external memory. Likewise, in the ADSP-2157x processors, the SHARC+ (Core 1) controls the boot function. The option for secure boot is available on all models.

Table 9. Boot Modes

SYS_BMODE[n] Setting[1, 2]	Boot Mode
000	No boot
001	SPI2 master
010	SPI2 slave
011	UART0 slave
100	Reserved
101	Reserved
110	Link0 slave

[1] SYS_BMODE2 pin is applicable only for the BGA package.
[2] Link0 slave boot is supported only on the BGA package.

Thermal Monitoring Unit (TMU)

The thermal monitoring unit (TMU) provides on-chip temperature measurement for applications that require substantial power consumption. The TMU is integrated into the processor die and digital infrastructure using an MMR-based system access to measure the die temperature variations in real-time.

TMU features include the following:

- On-chip temperature sensing
- Programmable over temperature and under temperature limits
- Programmable conversion rate
- Programmable clock source selection to run the sensor off an independent local clock
- Averaging feature available

Power Supplies

The processors have separate power supply connections for

- Internal (VDD_INT)
- External (VDD_EXT)
- USB (VDD_USB)
- HADC/TMU (VDD_HADC)
- DMC (VDD_DMC)

All power supplies must meet the specifications provided in Operating Conditions section. All external supply pins must be connected to the same power supply.

Power Management

As shown in Table 10, the processors support four different power domains, which maximizes flexibility while maintaining compliance with industry standards and conventions. There are no sequencing requirements for the various power domains, but all domains must be powered according to the appropriate specifications (see the Specifications section for processor operating conditions). If the feature or the peripheral is not used, refer to Table 25.

Table 12. ADSP-SC57x/ADSP-2157x 400-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
PPI0_D02	EPPI0 Data 2	D	PD_12
PPI0_D03	EPPI0 Data 3	D	PD_13
PPI0_D04	EPPI0 Data 4	D	PD_14
PPI0_D05	EPPI0 Data 5	D	PD_15
PPI0_D06	EPPI0 Data 6	C	PC_05
PPI0_D07	EPPI0 Data 7	D	PD_09
PPI0_D08	EPPI0 Data 8	C	PC_01
PPI0_D09	EPPI0 Data 9	C	PC_02
PPI0_D10	EPPI0 Data 10	C	PC_03
PPI0_D11	EPPI0 Data 11	C	PC_04
PPI0_D12	EPPI0 Data 12	E	PE_00
PPI0_D13	EPPI0 Data 13	C	PC_07
PPI0_D14	EPPI0 Data 14	C	PC_08
PPI0_D15	EPPI0 Data 15	E	PE_01
PPI0_FS1	EPPI0 Frame Sync 1 (HSYNC)	C	PC_14
PPI0_FS2	EPPI0 Frame Sync 2 (VSYNC)	C	PC_15
PPI0_FS3	EPPI0 Frame Sync 3 (FIELD)	C	PC_06
SPI0_CLK	SPI0 Clock	C	PC_01
SPI0_MISO	SPI0 Master In, Slave Out	C	PC_02
SPI0_MOSI	SPI0 Master Out, Slave In	C	PC_03
SPI0_RDY	SPI0 Ready	C	PC_05
$\overline{\text{SPI0\_SEL1}}$	SPI0 Slave Select Output 1	C	PC_04
$\overline{\text{SPI0\_SEL2}}$	SPI0 Slave Select Output 2	C	PC_05
$\overline{\text{SPI0\_SEL3}}$	SPI0 Slave Select Output 3	C	PC_06
$\overline{\text{SPI0\_SEL4}}$	SPI0 Slave Select Output 4	A	PA_09
$\overline{\text{SPI0\_SEL5}}$	SPI0 Slave Select Output 5	F	PF_05
$\overline{\text{SPI0\_SEL6}}$	SPI0 Slave Select Output 6	F	PF_04
$\overline{\text{SPI0\_SEL7}}$	SPI0 Slave Select Output 7	D	PD_05
$\overline{\text{SPI0\_SS}}$	SPI0 Slave Select Input	C	PC_04
SPI1_CLK	SPI1 Clock	C	PC_07
SPI1_MISO	SPI1 Master In, Slave Out	C	PC_08
SPI1_MOSI	SPI1 Master Out, Slave In	C	PC_09
SPI1_RDY	SPI1 Ready	C	PC_11
$\overline{\text{SPI1\_SEL1}}$	SPI1 Slave Select Output 1	C	PC_10
$\overline{\text{SPI1\_SEL2}}$	SPI1 Slave Select Output 2	C	PC_11
$\overline{\text{SPI1\_SEL3}}$	SPI1 Slave Select Output 3	F	PF_11
$\overline{\text{SPI1\_SEL4}}$	SPI1 Slave Select Output 4	A	PA_14
$\overline{\text{SPI1\_SEL5}}$	SPI1 Slave Select Output 5	B	PB_02
$\overline{\text{SPI1\_SEL6}}$	SPI1 Slave Select Output 6	D	PD_07
$\overline{\text{SPI1\_SEL7}}$	SPI1 Slave Select Output 7	D	PD_06
$\overline{\text{SPI1\_SS}}$	SPI1 Slave Select Input	C	PC_10
SPI2_CLK	SPI2 Clock	B	PB_14
SPI2_D2	SPI2 Data 2	B	PB_12
SPI2_D3	SPI2 Data 3	B	PB_13
SPI2_MISO	SPI2 Master In, Slave Out	B	PB_10
SPI2_MOSI	SPI2 Master Out, Slave In	B	PB_11
SPI2_RDY	SPI2 Ready	C	PC_00
$\overline{\text{SPI2\_SEL1}}$	SPI2 Slave Select Output 1	B	PB_15

Table 12. ADSP-SC57x/ADSP-2157x 400-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
TRACE0_D03	TRACE0 Trace Data 3	F	PF_03
TRACE0_D04	TRACE0 Trace Data 4	D	PD_10
TRACE0_D05	TRACE0 Trace Data 5	D	PD_11
TRACE0_D06	TRACE0 Trace Data 6	D	PD_12
TRACE0_D07	TRACE0 Trace Data 7	D	PD_13
TWI0_SCL	TWI0 Serial Clock	Not Muxed	TWI0_SCL
TWI0_SDA	TWI0 Serial Data	Not Muxed	TWI0_SDA
TWI1_SCL	TWI1 Serial Clock	Not Muxed	TWI1_SCL
TWI1_SDA	TWI1 Serial Data	Not Muxed	TWI1_SDA
TWI2_SCL	TWI2 Serial Clock	Not Muxed	TWI2_SCL
TWI2_SDA	TWI2 Serial Data	Not Muxed	TWI2_SDA
$\overline{\text{UART0\_CTS}}$	UART0 Clear to Send	D	PD_06
$\overline{\text{UART0\_RTS}}$	UART0 Request to Send	D	PD_05
$\overline{\text{UART0\_RX}}$	UART0 Receive	F	PF_09
$\overline{\text{UART0\_TX}}$	UART0 Transmit	F	PF_08
$\overline{\text{UART1\_CTS}}$	UART1 Clear to Send	E	PE_14
$\overline{\text{UART1\_RTS}}$	UART1 Request to Send	E	PE_00
$\overline{\text{UART1\_RX}}$	UART1 Receive	F	PF_11
$\overline{\text{UART1\_TX}}$	UART1 Transmit	F	PF_10
$\overline{\text{UART2\_CTS}}$	UART2 Clear to Send	A	PA_11
$\overline{\text{UART2\_RTS}}$	UART2 Request to Send	A	PA_10
$\overline{\text{UART2\_RX}}$	UART2 Receive	C	PC_13
$\overline{\text{UART2\_TX}}$	UART2 Transmit	C	PC_12
USB0_CLKIN	USB0 Clock/Crystal Input	Not Muxed	USB_CLKIN
USB0_DM	USB0 Data –	Not Muxed	USB0_DM
USB0_DP	USB0 Data +	Not Muxed	USB0_DP
USB0_ID	USB0 OTG ID	Not Muxed	USB0_ID
USB0_VBC	USB0 VBUS Control	Not Muxed	USB0_VBC
USB0_VBUS	USB0 Bus Voltage	Not Muxed	USB0_VBUS
USB0_XTAL	USB0 Crystal	Not Muxed	USB_XTAL
VDD_EXT	External Voltage Domain	Not Muxed	VDD_EXT
VDD_INT	Internal Voltage Domain	Not Muxed	VDD_INT
VDD_DMC	DMC VDD	Not Muxed	VDD_DMC
VDD_HADC	HADC/TMU VDD	Not Muxed	VDD_HADC
VDD_USB	USB VDD	Not Muxed	VDD_USB

[1] Signal is routed to the DAI0_PINnn pin through the DAI0_PBnn pin buffers using the SRU.

Table 25. ADSP-SC57x/ADSP-2157x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Internal Termination	Reset Drive	Power Domain	Description and Notes
DAI0_PIN16	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: DAI0 Pin 16 Notes: See note[2]
DAI0_PIN17	InOut	A	Programmable PullUp[3]	none	VDD_EXT	Desc: DAI0 Pin 17 Notes: See note[2]
DAI0_PIN18	InOut	A	Programmable PullUp[3]	none	VDD_EXT	Desc: DAI0 Pin 18 Notes: See note[2]
DAI0_PIN19	InOut	A	Programmable PullUp[3]	none	VDD_EXT	Desc: DAI0 Pin 19 Notes: See note[2]
DAI0_PIN20	InOut	A	Programmable PullUp[3]	none	VDD_EXT	Desc: DAI0 Pin 20 Notes: See note[2]
DMC0_A00	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 0 Notes: No notes
DMC0_A01	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 1 Notes: No notes
DMC0_A02	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 2 Notes: No notes
DMC0_A03	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 3 Notes: No notes
DMC0_A04	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 4 Notes: No notes
DMC0_A05	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 5 Notes: No notes
DMC0_A06	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 6 Notes: No notes
DMC0_A07	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 7 Notes: No notes
DMC0_A08	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 8 Notes: No notes
DMC0_A09	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 9 Notes: No notes
DMC0_A10	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 10 Notes: No notes
DMC0_A11	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 11 Notes: No notes
DMC0_A12	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 12 Notes: No notes
DMC0_A13	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 13 Notes: No notes
DMC0_A14	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 14 Notes: No notes
DMC0_A15	Output	B	none	L	VDD_DMC	Desc: DMC0 Address 15 Notes: No notes
DMC0_BA0	Output	B	none	L	VDD_DMC	Desc: DMC0 Bank Address Input 0 Notes: No notes
DMC0_BA1	Output	B	none	L	VDD_DMC	Desc: DMC0 Bank Address Input 1 Notes: No notes
DMC0_BA2	Output	B	none	L	VDD_DMC	Desc: DMC0 Bank Address Input 2 Notes: No notes

Table 25. ADSP-SC57x/ADSP-2157x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Internal Termination	Reset Drive	Power Domain	Description and Notes
PB_10	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 10 Notes: Connect to VDD_EXT or GND if not used
PB_11	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 11 Notes: Connect to VDD_EXT or GND if not used
PB_12	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 12 Notes: Connect to VDD_EXT or GND if not used
PB_13	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 13 Notes: Connect to VDD_EXT or GND if not used
PB_14	InOut	H	none	none	VDD_EXT	Desc: PORTB Position 14 Notes: Connect to VDD_EXT or GND if not used
PB_15	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTB Position 15 Notes: See note[2]
PC_00	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 0 Notes: See note[2]
PC_01	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 1 Notes: See note[2]
PC_02	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 2 Notes: See note[2]
PC_03	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 3 Notes: See note[2]
PC_04	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 4 Notes: See note[2]
PC_05	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 5 Notes: See note[2]
PC_06	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 6 Notes: See note[2]
PC_07	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 7 Notes: See note[2]
PC_08	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 8 Notes: See note[2]
PC_09	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 9 Notes: See note[2]
PC_10	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 10 Notes: See note[2]
PC_11	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 11 Notes: See note[2]
PC_12	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 12 Notes: See note[2]
PC_13	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 13 Notes: See note[2]
PC_14	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 14 Notes: See note[2]
PC_15	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTC Position 15 Notes: See note[2]

Table 25. ADSP-SC57x/ADSP-2157x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Internal Termination	Reset Drive	Power Domain	Description and Notes
PD_00	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 0 Notes: See note[2]
PD_01	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 1 Notes: See note[2]
PD_02	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 2 Notes: See note[2]
PD_03	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 3 Notes: See note[2]
PD_04	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 4 Notes: See note[2]
PD_05	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 5 Notes: See note[2]
PD_06	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 6 Notes: See note[2]
PD_07	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 7 Notes: See note[2]
PD_08	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 8 Notes: See note[2]
PD_09	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 9 Notes: See note[2]
PD_10	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 10 Notes: See note[2]
PD_11	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 11 Notes: See note[2]
PD_12	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 12 Notes: See note[2]
PD_13	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 13 Notes: See note[2]
PD_14	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 14 Notes: See note[2]
PD_15	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTD Position 15 Notes: See note[2]
PE_00	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 0 Notes: See note[2]
PE_01	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 1 Notes: See note[2]
PE_02	InOut	H	none	none	VDD_EXT	Desc: PORTE Position 2 Notes: Connect to VDD_EXT or GND if not used
PE_03	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 3 Notes: See note[2]
PE_04	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 4 Notes: See note[2]
PE_05	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 5 Notes: See note[2]
PE_06	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 6 Notes: See note[2]
PE_07	InOut	A	Programmable PullUp[1]	none	VDD_EXT	Desc: PORTE Position 7 Notes: See note[2]

Parameter		Conditions	Min	Typ	Max	Unit
I_{DD_IDLE}	V_{DD_INT} Current in Idle	f_{CCLK} = 500 MHz ASF_{SHARC1} = 0.32 ASF_{SHARC2} = 0.32 ASF_{A5} = 0.25 f_{SYSCLK} = 250 MHz $f_{SCLK0/1}$ = 125 MHz (Other clocks are disabled) No Peripheral or DMA activity T_J = 25°C V_{DD_INT} = 1.15 V		477		mA
I_{DD_TYP}	V_{DD_INT} Current	f_{CCLK} = 450 MHz ASF_{SHARC1} = 1.0 ASF_{SHARC2} = 1.0 ASF_{A5} = 0.67 f_{SYSCLK} = 225 MHz $f_{SCLK0/1}$ = 112.5 MHz (Other clocks are disabled) DMA data rate = 600 MB/s T_J = 25°C V_{DD_INT} = 1.1 V		890		mA
I_{DD_TYP}	V_{DD_INT} Current	f_{CCLK} = 500 MHz ASF_{SHARC1} = 1.0 ASF_{SHARC2} = 1.0 ASF_{A5} = 0.67 f_{SYSCLK} = 250 MHz $f_{SCLK0/1}$ = 125 MHz (Other clocks are disabled) DMA data rate = 600 MB/s T_J = 25°C V_{DD_INT} = 1.15 V		1031		mA
I_{DD_INT}[11]	V_{DD_INT} Current	f_{CCLK} > 0 MHz $f_{SCLK0/1} \geq 0$ MHz			See $I_{DD\_INT\_TOT}$ equation in the Total Internal Power Dissipation section.	mA

[1] Applies to all output and bidirectional pins except TWI, DMC, USB, and MLB.
[2] See the Output Drive Currents section for typical drive current capabilities.
[3] Applies to all DMC output and bidirectional signals in DDR2 mode.
[4] Applies to all DMC output and bidirectional signals in DDR3 mode.
[5] Applies to all DMC output and bidirectional signals in LPDDR mode.
[6] Applies to input pins: SYS_BMODE0-2, SYS_CLKIN0, SYS_CLKIN1, $\overline{\text{SYS\_HWRST}}$, JTG_TDI, JTG_TMS, and USB0_CLKIN.
[7] Applies to input pins with internal pull-ups: JTG_TDI, JTG_TMS, and JTG_TCK.
[8] Applies to signals: JTAG_TRST, USB0_VBUS.
[9] Applies to signals: PA0-15, PB0-15, PC0-15, PD0-15, PE0-15, PF0-11, DAI0_PINx, DMC0_DQx, DMC0_LDQS, DMC0_UDQS, $\overline{\text{DMC0\_LDQS}}$, $\overline{\text{DMC0\_UDQS}}$, SYS_FAULT, $\overline{\text{SYS\_FAULT}}$, JTG_TDO, USB0_ID, USB0_DM, USB0_DP, and USB0_VBC.
[10] Applies to all signal pins.
[11] See "Estimating Power for ADSP-SC57x/2157x SHARC+ Processors" (EE-397) for further information.

DDR2 SDRAM Clock and Control Cycle Timing

Table 43 and Figure 10 show DDR2 SDRAM clock and control cycle timing, related to the DMC.

Table 43. DDR2 SDRAM Clock and Control Cycle Timing, V_{DD_DMC} Nominal 1.8 V

Parameter		400 MHz[1] Min	400 MHz[1] Max	Unit
Switching Characteristics				
t_{CK}	Clock Cycle Time (CL = 2 Not Supported)	2.5		ns
$t_{CH(abs)}$[2]	Minimum Clock Pulse Width	0.48	0.52	t_{CK}
$t_{CL(abs)}$[2]	Maximum Clock Pulse Width	0.48	0.52	t_{CK}
t_{IS}	Control/Address Setup Relative to DMC0_CK Rise	175		ps
t_{IH}	Control/Address Hold Relative to DMC0_CK Rise	250		ps

[1] To ensure proper operation of DDR2, all the DDR2 requirements must be strictly followed. See "Interfacing DDR3/DDR2/LPDDR Memory to ADSP-SC5xx/215xx Processors" (EE-387).
[2] As per JESD79-2E definition.

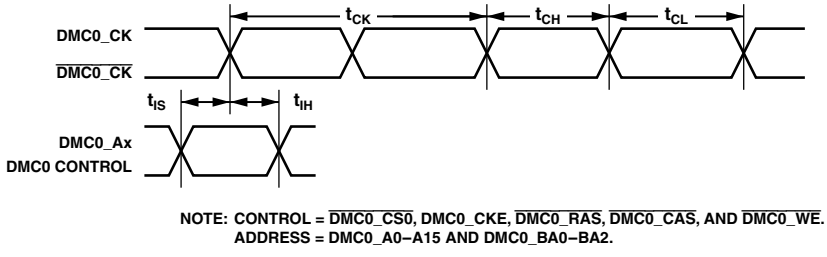

Figure 10. DDR2 SDRAM Clock and Control Cycle Timing

Mobile DDR SDRAM Read Cycle Timing

Table 47 and Figure 14 show mobile DDR SDRAM read cycle timing, related to the DMC.

Table 47. Mobile DDR SDRAM Read Cycle Timing, V_{DD_DMC} Nominal 1.8 V

Parameter		200 MHz[1]		Unit
		Min	Max	
Timing Requirements				
t_{QH}	DMC0_DQ, DMC0_DQS Output Hold Time From DMC0_DQS	1.75		ns
t_{DQSQ}	DMC0_DQS to DMC0_DQ Skew for DMC0_DQS and Associated DMC0_DQ Signals		0.4	ns
t_{RPRE}	Read Preamble	0.9	1.1	t_{CK}
t_{RPST}	Read Postamble	0.4	0.6	t_{CK}

[1] To ensure proper operation of LPDDR, all the LPDDR requirements must be strictly followed. See "Interfacing DDR3/DDR2/LPDDR Memory to ADSP-SC5xx/215xx Processors" (EE-387).

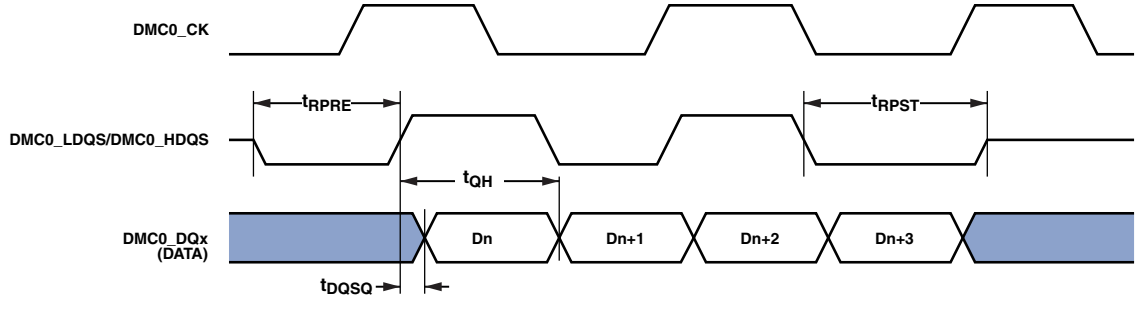

Figure 14. Mobile DDR SDRAM Controller Input AC Timing

DDR3 SDRAM Clock and Control Cycle Timing

Table 49 and Figure 16 show mobile DDR3 SDRAM clock and control cycle timing, related to the DMC.

Table 49. DDR3 SDRAM Clock and Control Cycle Timing, V_{DD_DMC} Nominal 1.5 V

Parameter		450 MHz[1]		Unit
		Min	Max	
Switching Characteristics				
t_{CK}	Clock Cycle Time (CL = 2 Not Supported)	2.22		ns
$t_{CH(abs)}$[2]	Minimum Clock Pulse Width	0.47	0.53	t_{CK}
$t_{CL(abs)}$[2]	Maximum Clock Pulse Width	0.47	0.53	t_{CK}
t_{IS}	Control/Address Setup Relative to DMC0_CK Rise	0.2		ns
t_{IH}	Control/Address Hold Relative to DMC0_CK Rise	0.275		ns

[1] To ensure proper operation of the DDR3, all the DDR3 requirements must be strictly followed. See "Interfacing DDR3/DDR2/LPDDR Memory to ADSP-SC5xx/215xx Processors" (EE-387).
[2] As per JESD79-3F definition.

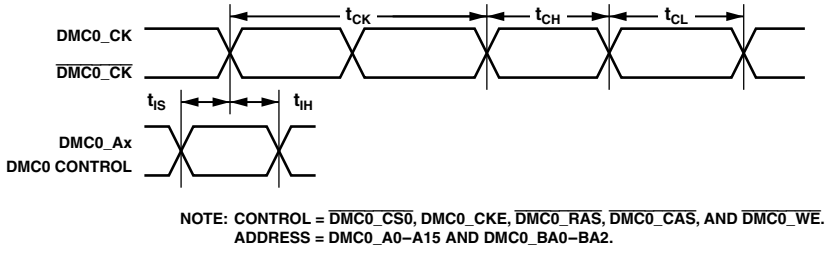

Figure 16. DDR3 SDRAM Clock and Control Cycle Timing

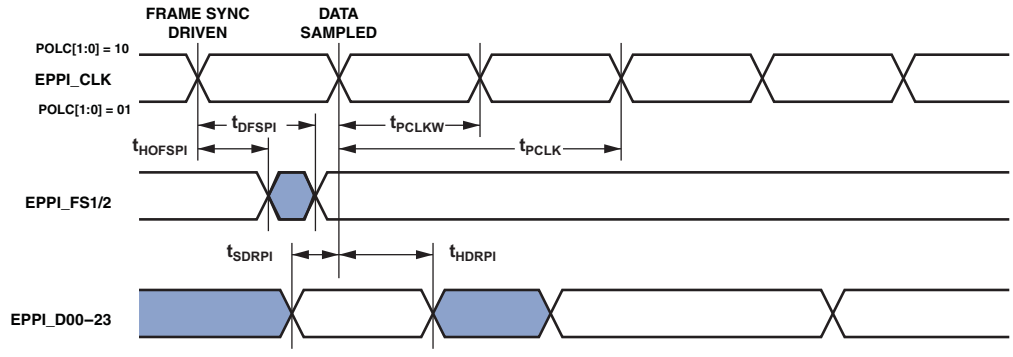

Figure 19. EPPI Internal Clock GP Receive Mode with Internal Frame Sync Timing

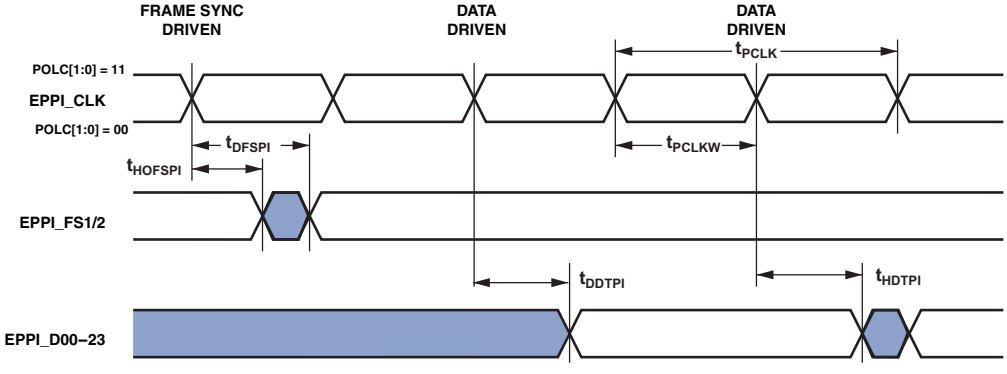

Figure 20. EPPI Internal Clock GP Transmit Mode with Internal Frame Sync Timing

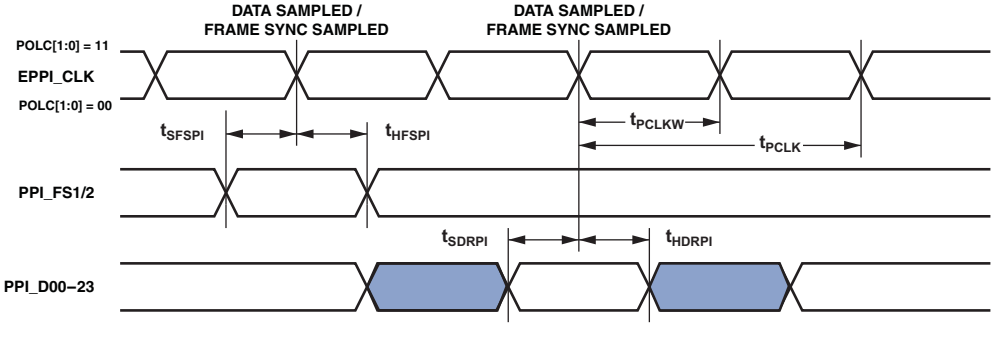

Figure 21. EPPI Internal Clock GP Receive Mode with External Frame Sync Timing

Link Ports (LPs)

In LP receive mode, the LP clock is supplied externally and is called $f_{LCLKREXT}$, therefore the period can be represented by

$$t_{LCLKREXT} = \frac{1}{f_{LCLKREXT}}$$

In LP transmit mode, the programmed LP clock ($f_{LCLKTPROG}$) frequency in megahertz is set by the following equation where VALUE is a field in the LP_DIV register that can be set from 1 to 255:

$$f_{LCLKTPROG} = \frac{f_{SCLK0}}{(VALUE \times 2)}$$

In the case where VALUE = 0, $f_{LCLKTPROG} = f_{SCLK0}$. For all settings of VALUE, the following equation is true:

$$t_{LCLKTPROG} = \frac{1}{f_{LCLKTPROG}}$$

Calculation of the link receiver data setup and hold relative to the link clock is required to determine the maximum allowable skew that can be introduced in the transmission path length difference between LPx_Dx and LPx_CLK. Setup skew is the maximum delay that can be introduced in LPx_Dx relative to LPx_CLK (setup skew = $t_{LCLKTWH}$ minimum − t_{DLDCH} − t_{SLDCL}). Hold skew is the maximum delay that can be introduced in LPx_CLK relative to LPx_Dx (hold skew = $t_{LCLKTWL}$ minimum − t_{HLDCH} − t_{HLDCL}).

Table 54. LPs—Receive[1]

Parameter		Min	Max	Unit
Timing Requirements				
$f_{LCLKREXT}$	LPx_CLK Frequency		112.5	MHz
t_{SLDCL}	Data Setup Before LPx_CLK Low	0.9		ns
t_{HLDCL}	Data Hold After LPx_CLK Low	1.4		ns
t_{LCLKEW}	LPx_CLK Period[2]	$t_{LCLKREXT}$ − 0.8		ns
$t_{LCLKRWL}$	LPx_CLK Width Low[2]	0.5 × $t_{LCLKREXT}$		ns
$t_{LCLKRWH}$	LPx_CLK Width High[2]	0.5 × $t_{LCLKREXT}$		ns
Switching Characteristic				
t_{DLALC}	LPx_ACK Low Delay After LPx_CLK Low[3]	1.5 × t_{SCLK0} + 4	2.5 × t_{SCLK0} + 12	ns

[1] Specifications apply to LP0 and LP1.
[2] This specification indicates the minimum instantaneous width or period that can be tolerated due to duty cycle variation or jitter on the external LPx_CLK. For the external LPx_CLK ideal maximum frequency, see the $f_{LCLKTEXT}$ specification in Table 27.
[3] LPx_ACK goes low with t_{DLALC} relative to rise of LPx_CLK after first byte, but does not go low if the link buffer of the receiver is not about to fill.

Table 57. SPORTs—Internal Clock[1]

Parameter		Min	Max	Unit
Timing Requirements				
t_{SFSI}	Frame Sync Setup Before SPTx_CLK (Externally Generated Frame Sync in either Transmit or Receive Mode)[2]	12		ns
t_{HFSI}	Frame Sync Hold After SPTx_CLK (Externally Generated Frame Sync in either Transmit or Receive Mode)[2]	–0.5		ns
t_{SDRI}	Receive Data Setup Before SPTx_CLK[2]	3.4		ns
t_{HDRI}	Receive Data Hold After SPTx_CLK[2]	1.5		ns
Switching Characteristics				
t_{DFSI}	Frame Sync Delay After SPTx_CLK (Internally Generated Frame Sync in Transmit or Receive Mode)[3]		3.5	ns
t_{HOFSI}	Frame Sync Hold After SPTx_CLK (Internally Generated Frame Sync in Transmit or Receive Mode)[3]	–2.5		ns
t_{DDTI}	Transmit Data Delay After SPTx_CLK[3]		3.5	ns
t_{HDTI}	Transmit Data Hold After SPTx_CLK[3]	–2.5		ns
$t_{SPTCLKIW}$	SPTx_CLK Width[4]	$0.5 \times t_{SPTCLKPROG} - 2$		ns
t_{SPTCLK}	SPTx_CLK Period[4]	$t_{SPTCLKPROG} - 1.5$		ns

[1] Specifications apply to all four SPORTs.
[2] Referenced to the sample edge.
[3] Referenced to drive edge.
[4] See Table 27 for details on the minimum period that can be programmed for $t_{SPTCLKPROG}$.

ADC Controller Module (ACM) Timing

Table 77 and Figure 48 describe ACM operations.

When internally generated, the programmed ACM clock ($f_{ACLKPROG}$) frequency in megahertz is set by the following equation where CKDIV is a field in the ACM_TC0 register and ranges from 1 to 255:

$$f_{ACLKPROG} = \frac{f_{SCLK1}}{CKDIV + 1}$$

$$t_{ACLKPROG} = \frac{1}{f_{ACLKPROG}}$$

Setup cycles (SC) in Table 77 is also a field in the ACM_TC0 register and ranges from 0 to 4095. Hold Cycles (HC) is a field in the ACM_TC1 register that ranges from 0 to 15.

Table 77. ACM Timing

Parameter		Min	Max	Unit
Timing Requirements				
t_{SDR}	SPORT DRxPRI/DRxSEC Setup Before ACMx_CLK	3.4		ns
t_{HDR}	SPORT DRxPRI/DRxSEC Hold After ACMx_CLK	1.5		ns
Switching Characteristics				
t_{SCTLCS}	ACM Controls (ACMx_A[4:0]) Setup Before Assertion of $\overline{CS}$	(SC + 1) × t_{SCLK1} – 4.88		ns
t_{HCTLCS}	ACM Control (ACMx_A[4:0]) Hold After Deassertion of $\overline{CS}$	HC × $t_{ACLKPROG}$ – 1		ns
t_{ACLKW}	ACM Clock Pulse Width[1]	(0.5 × $t_{ACLKPROG}$) – 1.6		ns
t_{ACLK}	ACM Clock Period[1]	$t_{ACLKPROG}$ – 1.5		ns
$t_{HCSACLK}$	$\overline{CS}$ Hold to ACMx_CLK Edge	–2.5		ns
$t_{SCSACLK}$	$\overline{CS}$ Setup to ACMx_CLK Edge	$t_{ACLKPROG}$ – 3.5		ns

[1] See Table 27 for details on the minimum period that can be programmed for $t_{ACLKPROG}$.

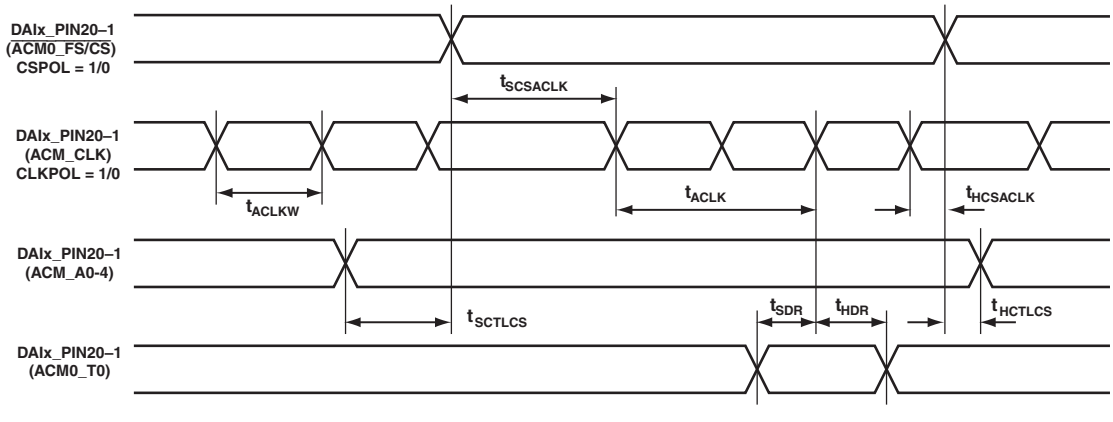

Figure 48. ACM Timing

S/PDIF Receiver

The following section describes timing as it relates to the S/PDIF receiver.

Internal Digital PLL Mode

In the internal digital PLL mode, the internal digital PLL generates the 512 × FS clock.

Table 90. S/PDIF Receiver Internal Digital PLL Mode Timing

Parameter		Min	Max	Unit
Switching Characteristics				
t_{DFSI}	Frame Sync Delay After Serial Clock		5	ns
t_{HOFSI}	Frame Sync Hold After Serial Clock	–2		ns
t_{DDTI}	Transmit Data Delay After Serial Clock		5	ns
t_{HDTI}	Transmit Data Hold After Serial Clock	–2		ns

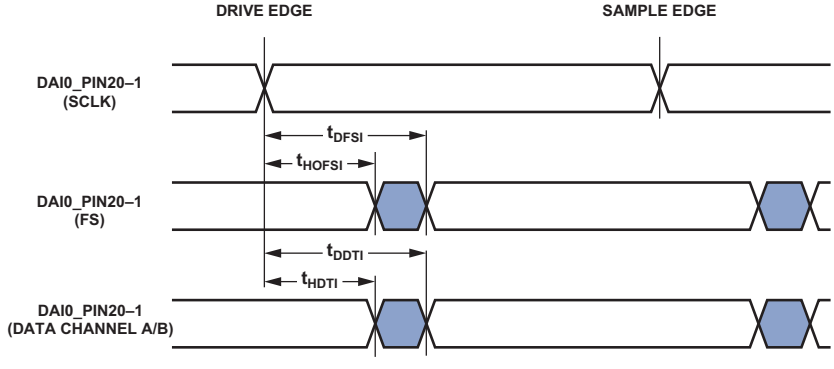

Figure 59. S/PDIF Receiver Internal Digital PLL Mode Timing

Debug Interface (JTAG Emulation Port) Timing

Table 95 and Figure 67 provide I/O timing related to the debug interface (JTAG Emulator Port).

Table 95. JTAG Emulation Port Timing

Parameter		Min	Max	Unit
Timing Requirements				
t_{TCK}	JTG_TCK Period	20		ns
t_{STAP}	JTG_TDI, JTG_TMS Setup Before JTG_TCK High	4		ns
t_{HTAP}	JTG_TDI, JTG_TMS Hold After JTG_TCK High	4		ns
t_{SSYS}	System Inputs Setup Before JTG_TCK High[1]	12		ns
t_{HSYS}	System Inputs Hold After JTG_TCK High[1]	5		ns
t_{TRSTW}	$\overline{\text{JTG\_TRST}}$ Pulse Width (measured in JTG_TCK cycles)[2]	4		T_{CK}
Switching Characteristics				
t_{DTDO}	JTG_TDO Delay From JTG_TCK Low		13.5	ns
t_{DSYS}	System Outputs Delay After JTG_TCK Low[3]		17	ns

[1] System Inputs = MLB0_CLKP, MLB0_DATP, MLB0_SIGP, DAI0_PIN20-01, DMC0_A15-0, DMC0_DQ15-0, $\overline{\text{DMC0\_RESET}}$, PA_15-0, PB_15-0, PC_15-0, PD_15-0, PE_15-0, PF_11-0, SYS_BMODE2-0, SYS_FAULT, $\overline{\text{SYS\_FAULT}}$, $\overline{\text{SYS\_RESOUT}}$, TWI2-0_SCL, TWI2-0_SDA2.

[2] 50 MHz maximum.

[3] System Outputs = DMC0_A15-0, DMC0_BA2-0, $\overline{\text{DMC0\_CAS}}$, DMC0_CK, DMC0_CKE, $\overline{\text{DMC0\_CS0}}$, DMC0_DQ15-0, DMC0_LDM, DMC0_LDQS, DMC0_ODT, $\overline{\text{DMC0\_RAS}}$, $\overline{\text{DMC0\_RESET}}$, DMC0_UDM, DMC0_UDQS, $\overline{\text{DMC0\_WE}}$, MLB0_DATP, MLB0_SIGP, PA_15-0, PB_15-0, PC_15-0, PD_15-0, PE_15-0, PF_11-0, SYS_BMODE2-0, SYS_CLKOUT, SYS_FAULT, $\overline{\text{SYS\_FAULT}}$, $\overline{\text{SYS\_RESOUT}}$.

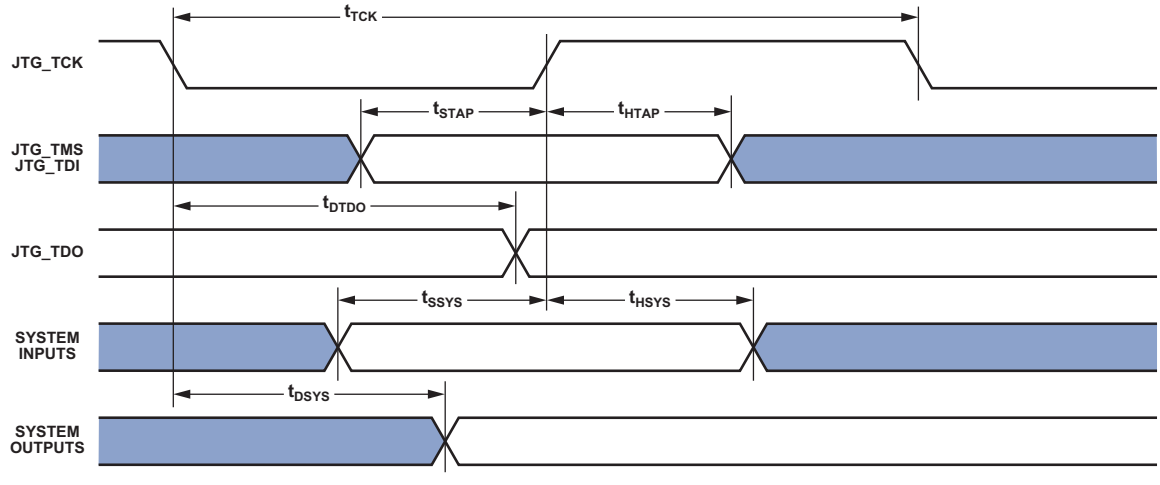

Figure 67. JTAG Port Timing

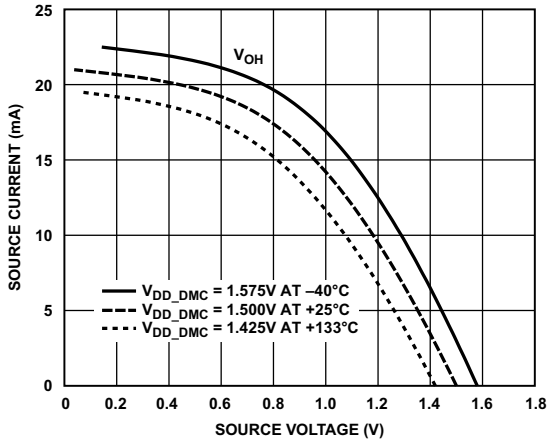

Figure 73. Driver Type B and Driver Type C (DDR3 Drive Strength 40 Ω)

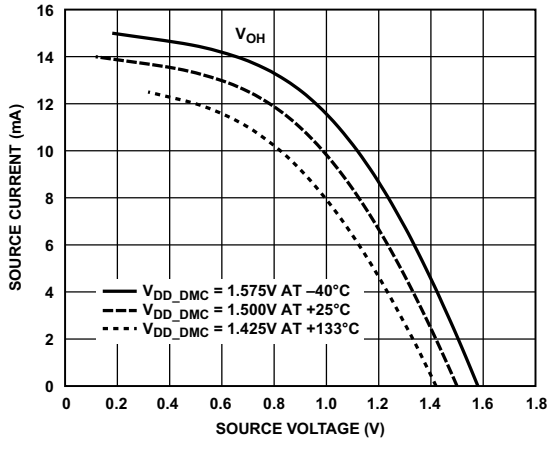

Figure 74. Driver Type B and Driver Type C (DDR3 Drive Strength 60 Ω)

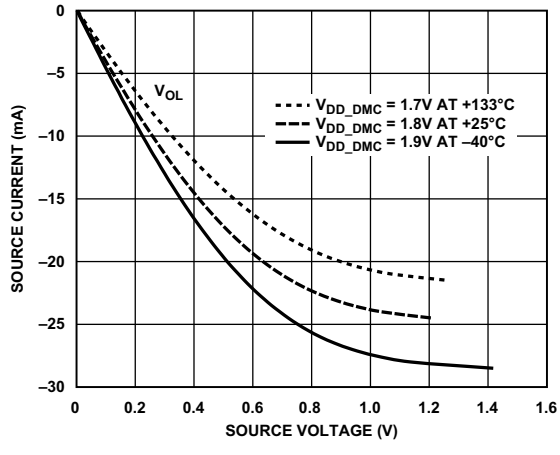

Figure 75. Driver Type B and Driver Type C (DDR2 Drive Strength 40 Ω)

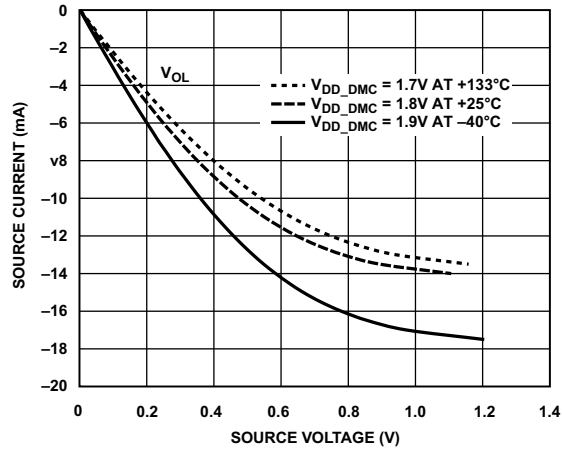

Figure 76. Driver Type B and Driver Type C (DDR2 Drive Strength 60 Ω)

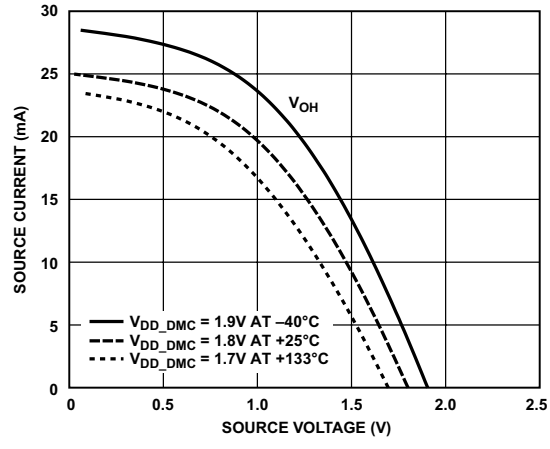

Figure 77. Driver Type B and Driver Type C (DDR2 Drive Strength 40 Ω)

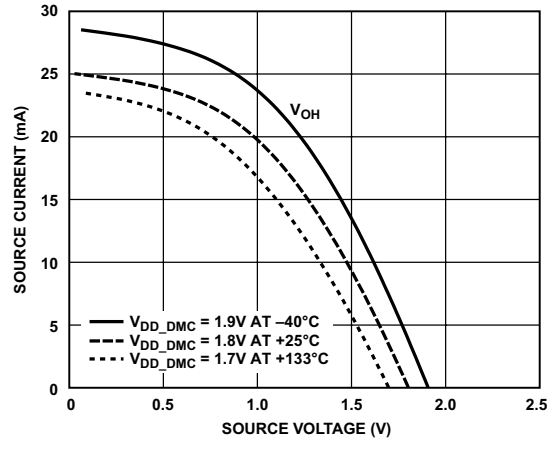

Figure 78. Driver Type B and Driver Type C (DDR2 Drive Strength 60 Ω)

ADSP-SC57x/ADSP-2157x 176-LEAD LQFP LEAD ASSIGNMENTS

The ADSP-SC57x/ADSP-2157x 176-Lead LQFP Lead Assignments (Numerical by Lead Number) table lists the 176-lead LQFP package by lead number.

The ADSP-SC57x/ADSP-2157x 176-Lead LQFP Lead Assignments (Alphabetical by Pin Name) table lists the 176-lead LQFP package by pin name.

ADSP-SC57x/ADSP-2157x 176-LEAD LQFP LEAD ASSIGNMENTS (NUMERICAL BY LEAD NUMBER)

Lead No.	Pin Name	Lead No.	Pin Name	Lead No.	Pin Name	Lead No.	Pin Name
01	VDD_INT	41	PD_11	81	$\overline{\text{SYS\_RESOUT}}$	121	DAI0_PIN03
02	GND	42	PD_10	82	VDD_INT	122	DAI0_PIN04
03	VDD_INT	43	PD_09	83	GND	123	DAI0_PIN01
04	PA_15	44	GND	84	VDD_EXT	124	VDD_INT
05	PA_14	45	GND	85	$\overline{\text{SYS\_FAULT}}$	125	GND
06	PA_13	46	VDD_EXT	86	SYS_BMODE0	126	VDD_EXT
07	VDD_INT	47	VDD_INT	87	SYS_BMODE1	127	DAI0_PIN02
08	PA_12	48	PD_08	88	VDD_INT	128	PB_15
09	VDD_EXT	49	PD_07	89	GND	129	VDD_INT
10	PA_10	50	PD_06	90	VDD_HADC	130	VDD_INT
11	PA_11	51	PD_05	91	HADC0_VIN0	131	GND
12	PC_15	52	VDD_INT	92	HADC0_VIN1	132	VDD_INT
13	PA_09	53	TWI0_SDA	93	HADC0_VREFN	133	GND
14	VDD_INT	54	TWI0_SCL	94	HADC0_VIN2	134	VDD_INT
15	GND	55	TWI1_SDA	95	HADC0_VIN3	135	JTG_TCK
16	VDD_INT	56	TWI1_SCL	96	HADC0_VREFP	136	JTG_TDO
17	PC_14	57	TWI2_SDA	97	GND	137	JTG_TDI
18	PC_13	58	TWI2_SCL	98	VDD_INT	138	JTG_TMS
19	PC_12	59	VDD_INT	99	GND	139	VDD_INT
20	PC_11	60	VDD_EXT	100	DAI0_PIN20	140	VDD_EXT
21	VDD_EXT	61	PD_04	101	DAI0_PIN19	141	PB_14
22	PC_10	62	PD_03	102	DAI0_PIN18	142	PB_13
23	PC_09	63	PD_02	103	VDD_INT	143	VDD_EXT
24	PC_08	64	PD_01	104	VDD_EXT	144	PB_12
25	PC_07	65	GND	105	DAI0_PIN17	145	VDD_INT
26	PC_06	66	VDD_INT	106	DAI0_PIN16	146	PB_11
27	PC_05	67	PD_00	107	DAI0_PIN15	147	VDD_EXT
28	PC_04	68	PA_08	108	DAI0_PIN14	148	PB_10
29	PC_03	69	PA_07	109	VDD_INT	149	VDD_EXT
30	VDD_INT	70	PA_06	110	DAI0_PIN13	150	VDD_INT
31	VDD_EXT	71	VDD_EXT	111	DAI0_PIN12	151	$\overline{\text{SYS\_HWRST}}$
32	PC_02	72	VDD_INT	112	DAI0_PIN11	152	VDD_EXT
33	PC_01	73	VDD_INT	113	DAI0_PIN10	153	$\overline{\text{JTG\_TRST}}$
34	PC_00	74	PA_05	114	VDD_INT	154	SYS_CLKIN0
35	PD_15	75	PA_04	115	VDD_EXT	155	SYS_XTAL0
36	PD_14	76	PA_03	116	DAI0_PIN09	156	VDD_INT
37	PD_13	77	PA_02	117	DAI0_PIN08	157	SYS_CLKOUT
38	VDD_EXT	78	VDD_EXT	118	DAI0_PIN06	158	VDD_EXT
39	VDD_INT	79	PA_01	119	DAI0_PIN07	159	PB_09
40	PD_12	80	PA_00	120	DAI0_PIN05	160	VDD_EXT

ADSP-SC57X/ADSP-2157X 176-LEAD LQFP LEAD ASSIGNMENTS (ALPHABETICAL BY PIN NAME)

Pin Name	Lead No.	Pin Name	Lead No.	Pin Name	Lead No.	Pin Name	Lead No.
DAI0_PIN01	123	PA_01	79	PC_15	12	VDD_EXT	149
DAI0_PIN02	127	PA_02	77	PD_00	67	VDD_EXT	152
DAI0_PIN03	121	PA_03	76	PD_01	64	VDD_EXT	158
DAI0_PIN04	122	PA_04	75	PD_02	63	VDD_EXT	160
DAI0_PIN05	120	PA_05	74	PD_03	62	VDD_EXT	164
DAI0_PIN06	118	PA_06	70	PD_04	61	VDD_EXT	167
DAI0_PIN07	119	PA_07	69	PD_05	51	VDD_EXT	171
DAI0_PIN08	117	PA_08	68	PD_06	50	VDD_HADC	90
DAI0_PIN09	116	PA_09	13	PD_07	49	VDD_INT	01
DAI0_PIN10	113	PA_10	10	PD_08	48	VDD_INT	03
DAI0_PIN11	112	PA_11	11	PD_09	43	VDD_INT	07
DAI0_PIN12	111	PA_12	08	PD_10	42	VDD_INT	14
DAI0_PIN13	110	PA_13	06	PD_11	41	VDD_INT	16
DAI0_PIN14	108	PA_14	05	PD_12	40	VDD_INT	30
DAI0_PIN15	107	PA_15	04	PD_13	37	VDD_INT	39
DAI0_PIN16	106	PB_00	174	PD_14	36	VDD_INT	47
DAI0_PIN17	105	PB_01	173	PD_15	35	VDD_INT	52
DAI0_PIN18	102	PB_02	172	SYS_BMODE0	86	VDD_INT	59
DAI0_PIN19	101	PB_03	169	SYS_BMODE1	87	VDD_INT	66
DAI0_PIN20	100	PB_04	168	SYS_CLKIN0	154	VDD_INT	72
GND	02	PB_05	166	SYS_CLKOUT	157	VDD_INT	73
GND	15	PB_06	165	$\overline{\text{SYS\_FAULT}}$	85	VDD_INT	82
GND	44	PB_07	162	$\overline{\text{SYS\_HWRST}}$	151	VDD_INT	88
GND	45	PB_08	161	$\overline{\text{SYS\_RESOUT}}$	81	VDD_INT	98
GND	65	PB_09	159	SYS_XTAL0	155	VDD_INT	103
GND	83	PB_10	148	TWI0_SCL	54	VDD_INT	109
GND	89	PB_11	146	TWI0_SDA	53	VDD_INT	114
GND	97	PB_12	144	TWI1_SCL	56	VDD_INT	124
GND	99	PB_13	142	TWI1_SDA	55	VDD_INT	129
GND	125	PB_14	141	TWI2_SCL	58	VDD_INT	130
GND	131	PB_15	128	TWI2_SDA	57	VDD_INT	132
GND	133	PC_00	34	VDD_EXT	09	VDD_INT	134
GND	176	PC_01	33	VDD_EXT	21	VDD_INT	139
GND	177[1]	PC_02	32	VDD_EXT	31	VDD_INT	145
HADC0_VIN0	91	PC_03	29	VDD_EXT	38	VDD_INT	150
HADC0_VIN1	92	PC_04	28	VDD_EXT	46	VDD_INT	156
HADC0_VIN2	94	PC_05	27	VDD_EXT	60	VDD_INT	163
HADC0_VIN3	95	PC_06	26	VDD_EXT	71	VDD_INT	170
HADC0_VREFN	93	PC_07	25	VDD_EXT	78	VDD_INT	175
HADC0_VREFP	96	PC_08	24	VDD_EXT	84		
JTG_TCK	135	PC_09	23	VDD_EXT	104		
JTG_TDI	137	PC_10	22	VDD_EXT	115		
JTG_TDO	136	PC_11	20	VDD_EXT	126		
JTG_TMS	138	PC_12	19	VDD_EXT	140		
$\overline{\text{JTG\_TRST}}$	153	PC_13	18	VDD_EXT	143		
PA_00	80	PC_14	17	VDD_EXT	147		

[1] Pin 177 is the GND supply (see Figure 91) for the processor; this pad must connect to GND.